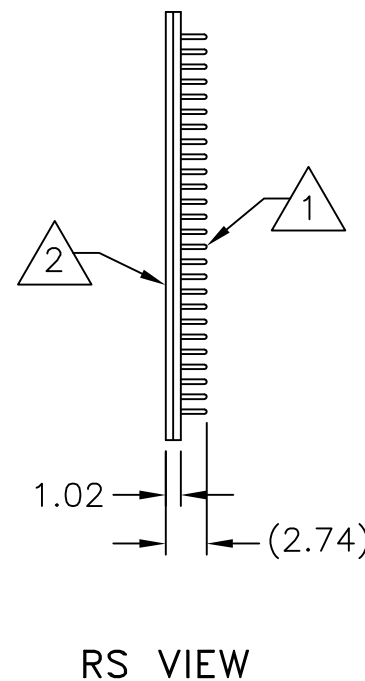
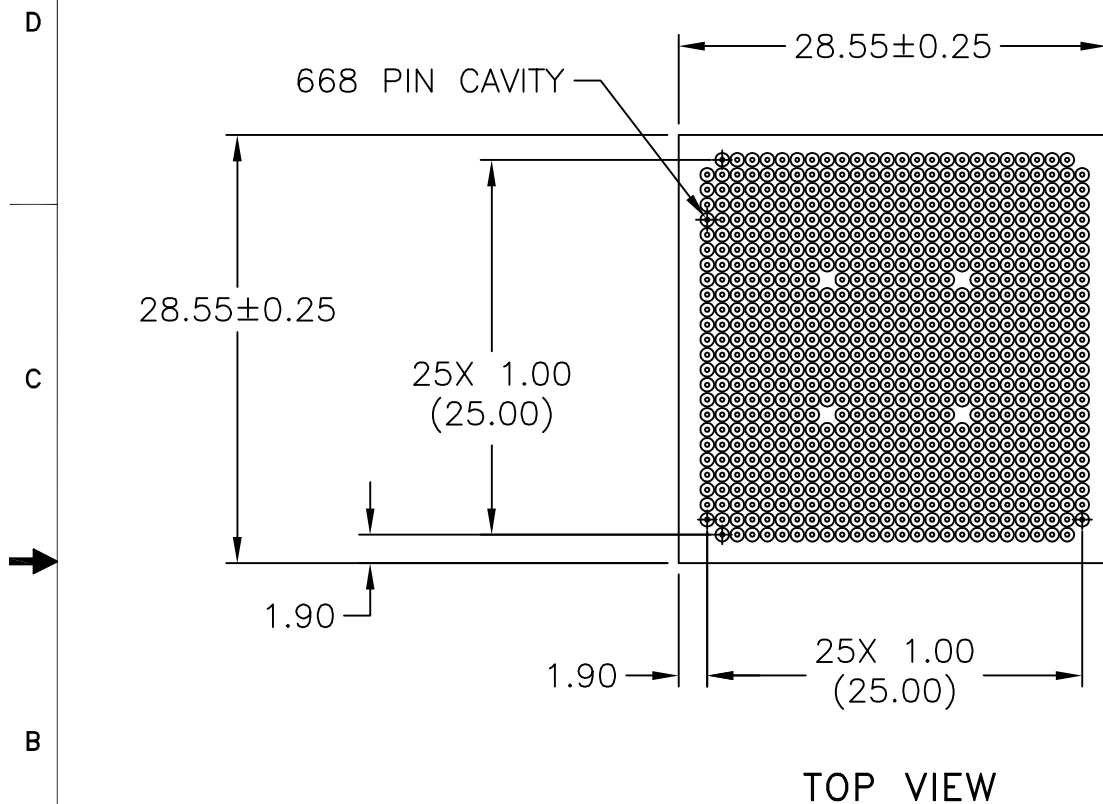


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REVISION HISTORY				
REV	DESCRIPTION	ECN	DATE	APRVD
1	R & D RELEASE			



NOTES:

- 1. PINS  $\phi$ .30 [.012] X 2.74 [.108] LONG.  
MATERIAL: PHOSPHOR BRONZE.  
PLATING: HARD GOLD OVER NICKEL.
- 2. INSULATOR MATERIAL: FR4, BLACK,  $T_g$ 125°C.

**METRIC CUSTOMER APPLICATION DRAWING**

UNLESS OTHERWISE SPECIFIED: DIMENSIONS ARE IN MILLIMETERS [ALTERNATE] DIMENSIONS ARE IN INCHES TOLERANCES: ANGLES: $\pm 10^\circ$ FRACTIONS: $\pm 1/64$ DECIMALS: .X $\pm .25$ .XX $\pm .13$ .XXX $\pm .013$	CONTRACT NO.	 <b>INTERCONNECT SYSTEMS INC.</b> 708 VIA ALONDRA, CAMARILLO, CA 93012
	DRAWN BY H. RANGLES	
DESIGNER H. RANGLES	DATE 10/28/04	TITLE HiLo PIN BASE, BGA ATTACH, FR4, 26 X 26, 668 PINS, 1.00mm PITCH, FOR P/N: HLP-260668-B-10
CHECKER	DATE	SIZE A
QA	DATE	SCALE 2/1
PROCESS ENG.	DATE	DRAWING NO.
		REV 1